Docket No. 217636US3 2 444 20 700 2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Shigeo KOUZUKI, et al.

SERIAL NO: 10/020,928

FILED: 12/19/01

FOR: SEMICONDUCTOR DEVICE AND PACKAGE THEREFOR

LETTER TO THE OFFICIAL DRAFTSMAN

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, DC 20231

SIR:

In response to the Notice to File Missing Parts of Nonprovisional Application, attached hereto please find __9_ sheets of Substitute Formal Drawings. It is requested that the enclosed __9_ sheets of Substitute Formal Drawings be entered to replace the drawings previously filed in this application.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

22850

CIM:dnf (703) 413-3000 Fax: (703) 412-2220 C. Irvin McClelland Registration No: 21,124 Attorney of Record SERIAL NO: 10/020,928 INV: Shigeo KOUZUKI, et al. DOCKET # 217636US3 SHEET 1_ OF 9

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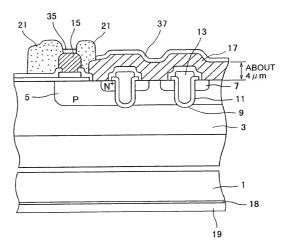
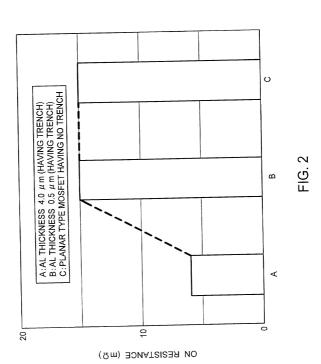


FIG. 1



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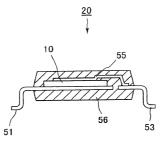


FIG. 3A

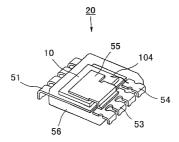
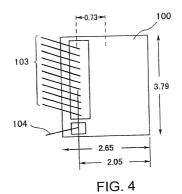


FIG. 3B



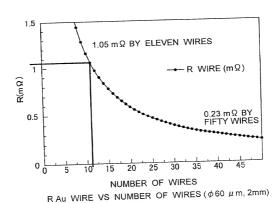
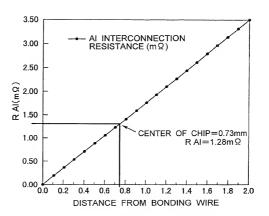


FIG. 5



AI INTERCONNECTION RESISTANCE ON SURFACE OF CHIP

FIG. 6



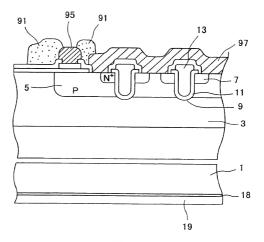


FIG. 7

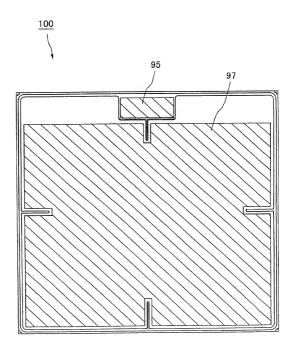


FIG. 8



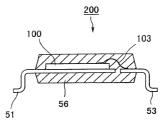


FIG. 9A

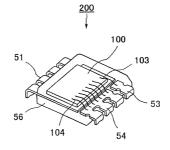


FIG. 9B

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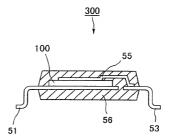


FIG. 10A

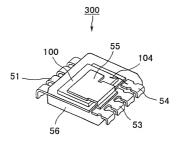


FIG. 10B